

Dear customer,

With this Infineon Technologies AG Information Note we would like to inform you about the following

Change of packing for CIPOS™ Micro

N° 034/21

Change of packing for CIPOS™ Micro

► Products affected

Please refer to attached affected product list 1_cip03421



► Detailed change information

Subject For through-hole CIPOS Micro devices packing is changed from dry to non-dry.

Reason Packing standardization.

Description

Old

- MBB (moisture barrier bag)

New

- ESD shield bag

► Product identification

No change in SP Ordering Number or Orderable Part Number (OPN).

► Impact of change

No impact on electrical performance of the products as only the packing of the products will be changed.

► Attachments

Affected product list 1_cip03421

► Intended start of delivery

2021-08-16

Existing stock will be depleted first, earlier deliveries possible with Customer agreement

If you have any questions, please do not hesitate to contact your local sales office.